

Increased Circuit Density











Overview

Everything is becoming digital and the electronics that drive digitization are expected to become even more thinner, lighter, and powerful. Smaller form factors, more stylish designs, and increasingly discrete applications demand Original Equipment Manufacturers to use thinner Printed Circuit Boards (PCBs) that do not compromise on quality or robustness. Multek offers customers many ways in which board thickness can be reduced.

Features

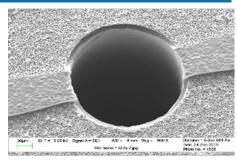
- Through hole without capture pad
- Through hole with or without trace connection
- Through hole split into two halves
- Each half via connected to an independent trace

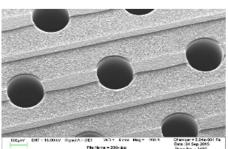
PCB Designs:

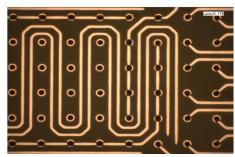
Applications

- Connectivity application
- Surface electrical isolation

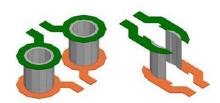
Landless Via

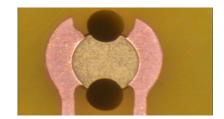


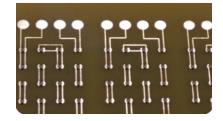




Split Via







About Multek

Multek, a wholly owned subsidiary of Suzhou Dongshan Precision Manufacturing Co.,Ltd. (DSBJ), is a leading value-add manufacturer of printed circuit board technologies offering a broad spectrum of PCB engineering and manufacturing expertise including high density interconnect, multilayer, flexible circuit and assembly solutions. Built upon a foundation of rapid response, technology leadership and high reliability solutions for PCB fabrication electronics design and manufacturing, Multek enables customers to take products to market quickly through early engineering, advanced technology new product introduction, and volume production through a full range of high-performance products, materials, and solutions. For more information, please email sales.pcb@multek.com or visit www.multek.com.

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